

ST17H66T

Bluetooth Low Energy (BLE) System on Chip

Key Feature

- 32-bit Low-power Processor
- Memory
- ▶ 96K ROM
- > 32KB SRAM, all programmable retention in sleep mode
- > 16KB OTP (embedded change pump)
- 9 General Purpose I/O Pins
- All configurable as serial interface and programmable IO MUX function mapping
- > All pins can be configured for wake-up
- > All pins for triggering interrupt
- > 3 Quadrature Decoder (QDEC)
- > 6-channel PWM
- ▶ 12C
- > 2-channel SPI (a master and a slave)
- > 2-channel UART
- > SWD
- 10-channel 12-bit ADC
- · 4-channel 32-bit Timer, 1 Watchdog Timer
- Real Timer Counter (RTC)
- Power, Clock and Reset Controller
- Flexible Power Management
- > Operating Voltage range 1.8V to 4.3V
- > Embedded LDOs
- > Battery monitor: support low battery
- > Support lithium battery charging
- Power Consumption
- 2.8uA@OFF Mode (IO wake up only)

- > 4uA@Sleep Mode with 32KHz RTC
- > Receive Mode: 10mA@3.3V Power Supply
- Transmit Mode: 10mA (0dBm output power)
- RC Oscillator Hardware Calibrations
- > 32Khz RC osc for RTC with +/-200ppm accuracy
- > 32MHz RC osc for HCLK with 3% accuracy
- High Speed Throughput
- > Support BLE 2Mbps Protocol
- > Support Data Length Extension
- > Throughput up to 1.6Mbps (DLE+2Mbps)
- 2.4 GHz Transceiver
- > Support BLE 5.0 RF PHY 1Mbps/2Mbps
- > Proprietary 500K Protocol Stack
- FSK with configurable Gaussian filter (configurable modulation index)
- > Sensitivity:
 - -94dBm@BLE 1Mbps data rate
 - -91dBm@BLE 2Mbps data rate
- > Tx power -20 to +6dBm in 3dB steps
- Single-pin antenna: no RF matching or Rx/Tx switching required
- > RSSI (1dB resolution)
- AES-128 Encryption Hardware
- Operating Temperature: -40°C ~+125 °C
- RoHS Package: TSSOP16

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1 Introduction

ST17H66T is a System on Chip (SoC) for Bluetooth® low energy applications. It has high-performance low-power 32-bit processer with 32K retention SRAM, 96KB ROM, 16KB OTP, and an ultra-low power, high performance, multi-mode radio. Also, ST17H66T can support BLE with security, Serial peripheral IO and integrated application IP enables customer product to be built with minimum bill-of-material (BOM) cost.

2 Pin Assignments and Functions

This section describes the pin assignment and the pin functions for the package types of TSSOP16.

2.1 Pin Assignment(TSSOP16)

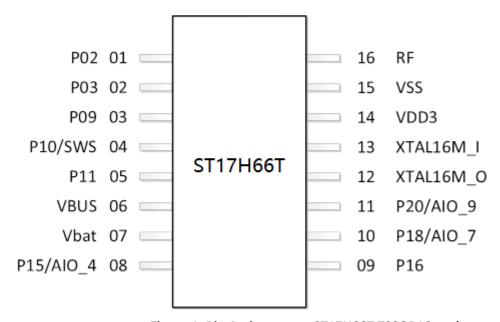


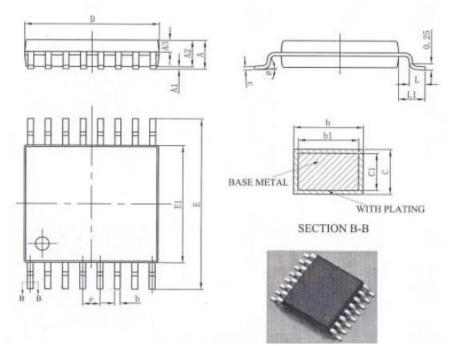
Figure 1: Pin Assignment – ST17H66T TSSOP16 package

2.2 Pin Functions

Pin	Pin name	Description		
1	P02	GPIO 02		
2	P03	GPIO 03		
3	P09	GPIO 09		
4	P10/SWS	GPIO 10/SWS		
5	P11	GPIO 11		
6	VBUS	VBUS		
7	Vbat	Vbat		
8	P15/AIO_4	GPIO 15/ADC input 4		
9	P16/XTAL32K_I	GPIO 16/ADC input 5/32.768KHz crystal input		
10	P18/AIO_7/XTAL32K_O	GPIO 18/ADC input 7/32.768KHz crystal output		
11	P20/AIO_9	GPIO 20/ADC input 9		
12	XTAL16M_O	16MHz crystal output		
13	XTAL16M_I	16MHz crystal input		
14	VDD3	3.3V power supply		
15	VSS	GND		
16	RF	RF antenna		

Table 1: Pin Functions of ST17H66T TSSOP16 package

3 Package dimensions



SYMBOL	MILLIMETER			
STMBOL	MIN	NOM	MAX	
A	_	_	1.20	
Al	0.05	_	0.15	
A2	0.90	1.00	1.05	
A3	0.39	0.44	0.49	
b	0.20	_	0.28	
b1	0.19	0.22	0.25	
c	0.13	_	0.17	
cl	0.12	0.13	0.14	
D	4.90	5.00	5.10	
E	6.20	6.40	6.60	
E1	4.30	4.40	4.50	
e	0.65BSC			
L	0.45	0.60	0.75	
LI	1.00BSC			
0	0		8'	

Figure 2: TSSOP16 package dimensions